

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Q1 N-CHANNEL	Q2 P-CHANNEL	Units
Drain-Source Voltage			V _{DSS}	12	-12	V
Gate-Source Voltage			V _{GSS}	±8	±8	V
Continuous Drain Current (Note 5) V _{GS} = 4.5V	Steady State	T _A = +25°C T _A = +70°C	I _D	5.6 4.4	-3.8 -3.0	A
	t < 5s	T _A = +25°C T _A = +70°C	I _D	7.2 5.8	-5.0 -4.0	A
Maximum Continuous Body Diode Forward Current (Note 5)			I _S	1	-1	A
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)			I _{DM}	20	-15	A
Avalanche Current (L = 0.1mH)			I _{AS}	15	-12	A
Avalanche Energy (L = 0.1mH)			E _{AS}	12	8	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	Steady State	P _D	1.4	W
	t < 5s		2.2	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R _{θJA}	91	°C/W
	t < 5s		55	
Thermal Resistance, Junction to Case		R _{θJC}	20	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Note: 5. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.

Electrical Characteristics Q1 N-CHANNEL (@T_A = +25°C, unless otherwise specified.)

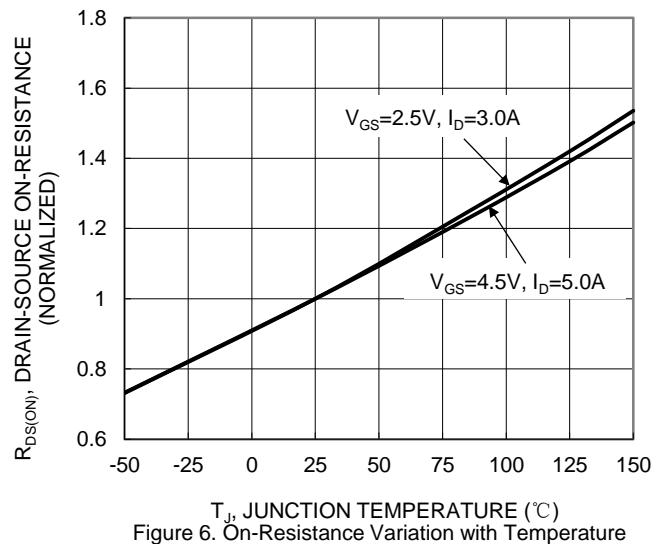
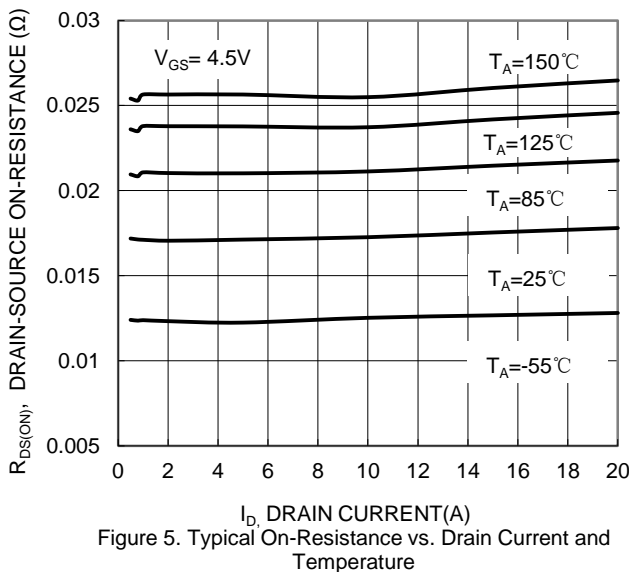
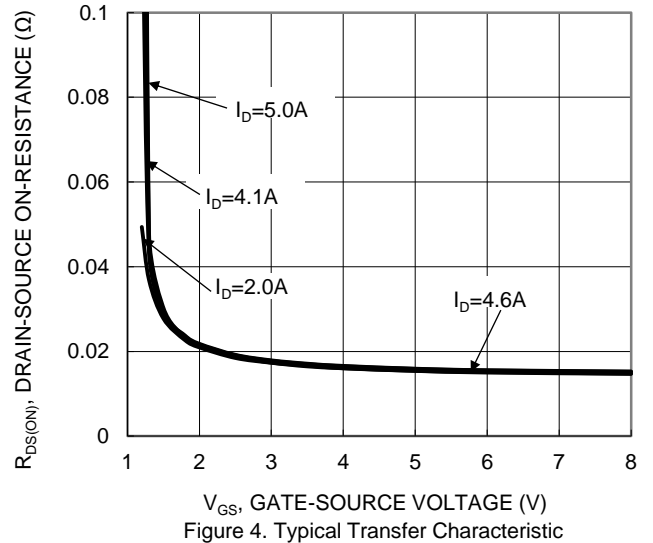
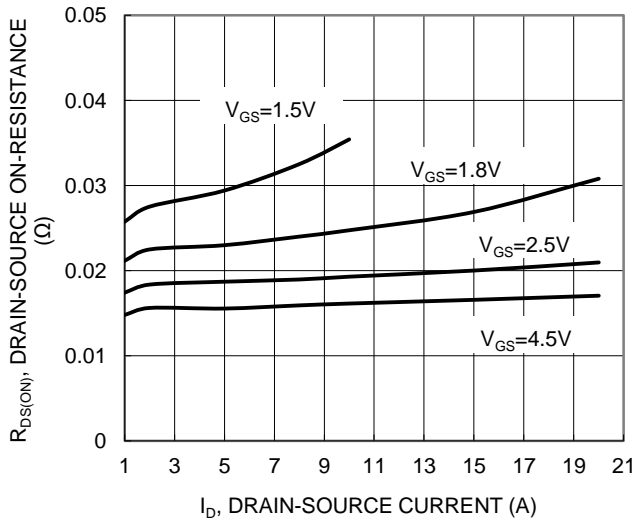
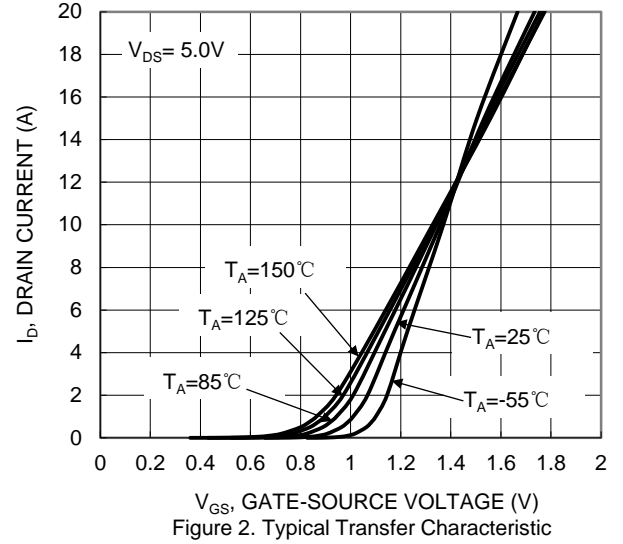
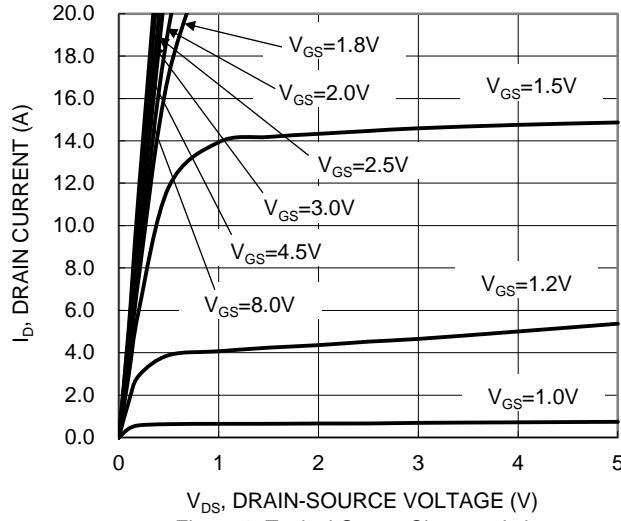
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	12	—	—	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	—	—	1.0	μA	V _{DS} = 12V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±8V, V _{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(TH)}	0.4	—	1	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	17	29	mΩ	V _{GS} = 4.5V, I _D = 5A
		—	20	34		V _{GS} = 2.5V, I _D = 4.6A
		—	24	44		V _{GS} = 1.8V, I _D = 4.1A
		—	30	65		V _{GS} = 1.5V, I _D = 2A
Diode Forward Voltage	V _{SD}	—	0.6	1.2	V	V _{GS} = 0V, I _S = 1A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{iss}	—	914	—	pF	V _{DS} = 6V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	132	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	119	—	pF	
Gate Resistance	R _g	—	1.26	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = 4.5V)	Q _g	—	10.5	—	nC	V _{DS} = 6V, I _D = 6.5A
Total Gate Charge (V _{GS} = 8V)		—	19.6	—	nC	
Gate-Source Charge	Q _{gs}	—	1.2	—	nC	
Gate-Drain Charge	Q _{gd}	—	1.6	—	nC	
Turn-On Delay Time	t _{D(ON)}	—	5.0	—	ns	V _{DD} = 6V, V _{GS} = 4.5V, R _L = 1.2Ω, R _G = 1Ω
Turn-On Rise Time	t _r	—	10.5	—	ns	
Turn-Off Delay Time	t _{D(OFF)}	—	16.6	—	ns	
Turn-Off Fall Time	t _f	—	4.1	—	ns	

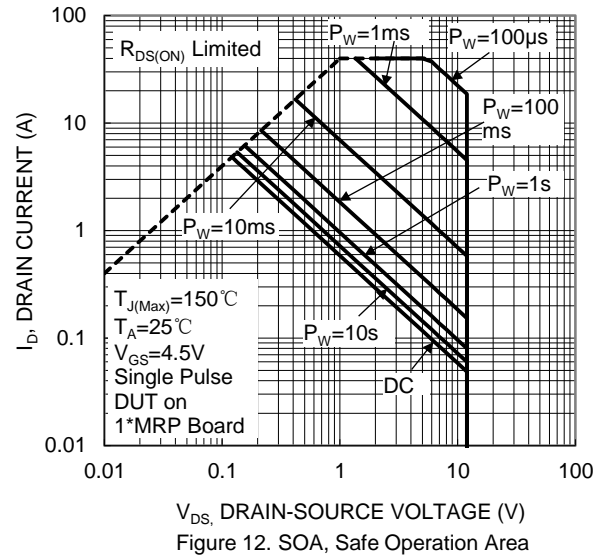
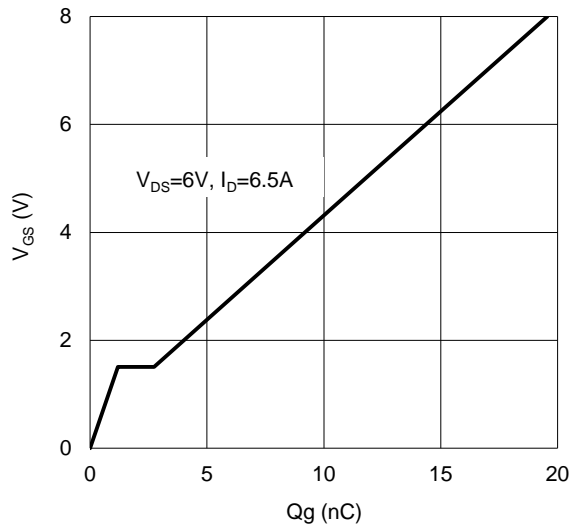
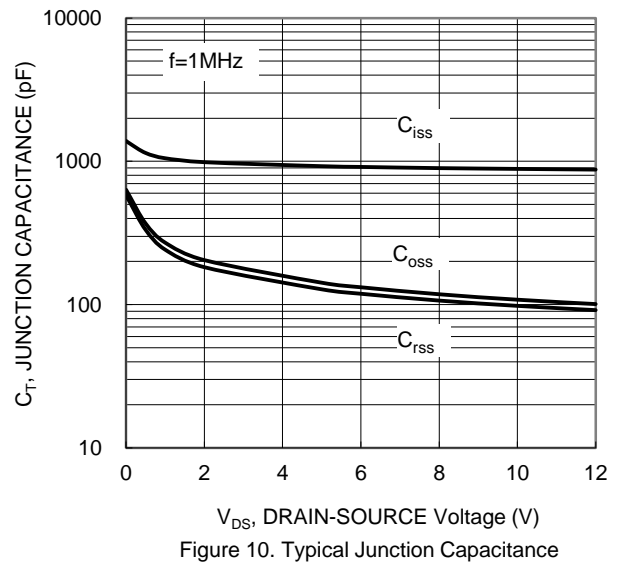
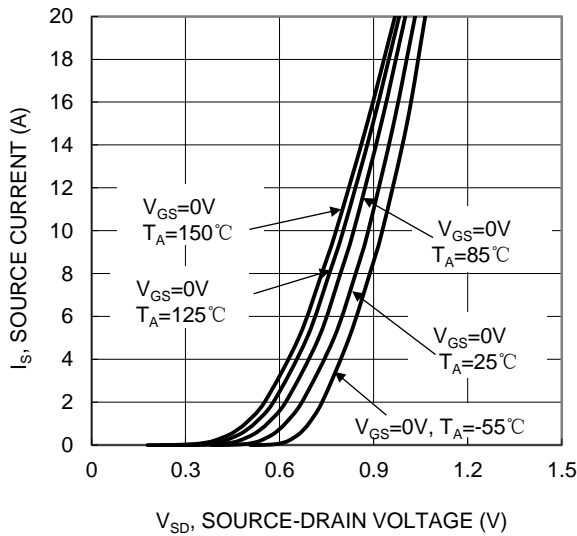
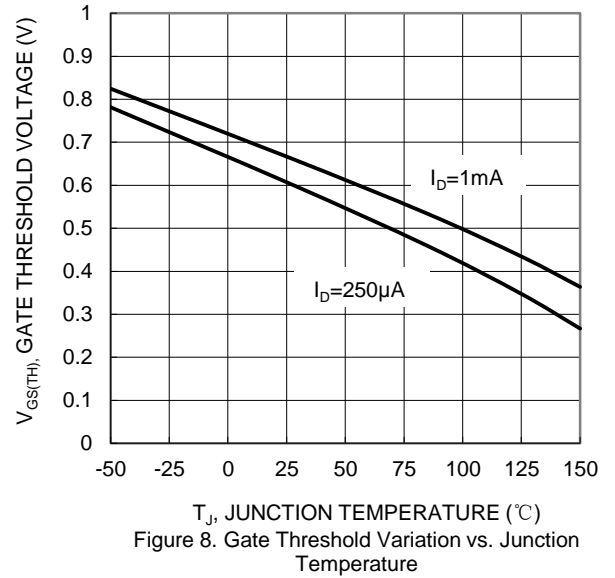
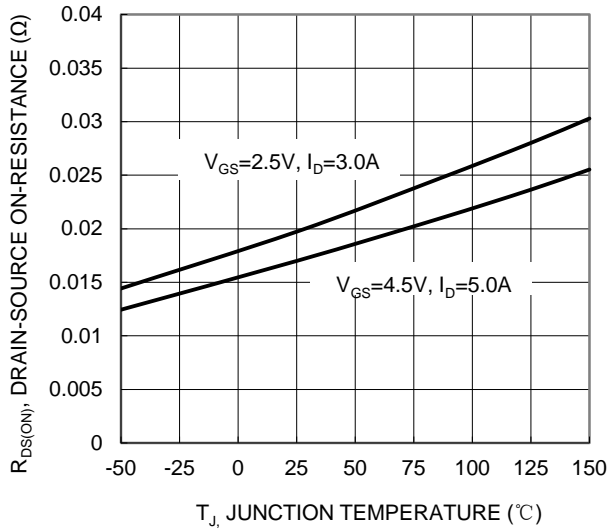
Electrical Characteristics Q2 P-CHANNEL (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	-12	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	—	—	-1.0	μA	V _{DS} = -12V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±8V, V _{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(TH)}	-0.4	—	-1	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	37	61	mΩ	V _{GS} = -4.5V, I _D = -3.6A
		—	47	81		V _{GS} = -2.5V, I _D = -3.2A
		—	63	115		V _{GS} = -1.8V, I _D = -1A
		—	90	210		V _{GS} = -1.5V, I _D = -1A
Diode Forward Voltage	V _{SD}	—	-0.65	-1.2	V	V _{GS} = 0V, I _S = -1A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{iss}	—	915	—	pF	V _{DS} = -6V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	225	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	183	—	pF	
Gate Resistance	R _g	—	56.9	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = -4.5V)	Q _g	—	10.7	—	nC	V _{DS} = -6V, I _D = -4.3A
Total Gate Charge (V _{GS} = -8V)		—	17.9	—	nC	
Gate-Source Charge	Q _{gs}	—	1.7	—	nC	
Gate-Drain Charge	Q _{gd}	—	3.0	—	nC	
Turn-On Delay Time	t _{D(ON)}	—	5.7	—	ns	V _{DD} = -6V, V _{GS} = -4.5V, R _L = 1.6Ω, R _G = 1Ω
Turn-On Rise Time	t _r	—	11.5	—	ns	
Turn-Off Delay Time	t _{D(OFF)}	—	27.8	—	ns	
Turn-Off Fall Time	t _f	—	26.4	—	ns	

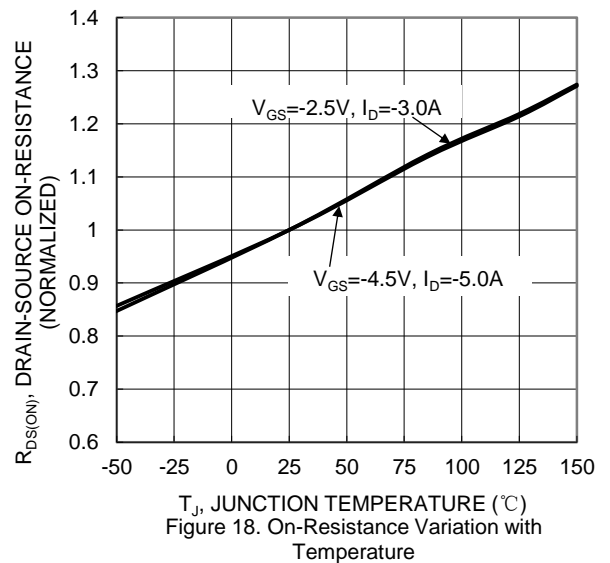
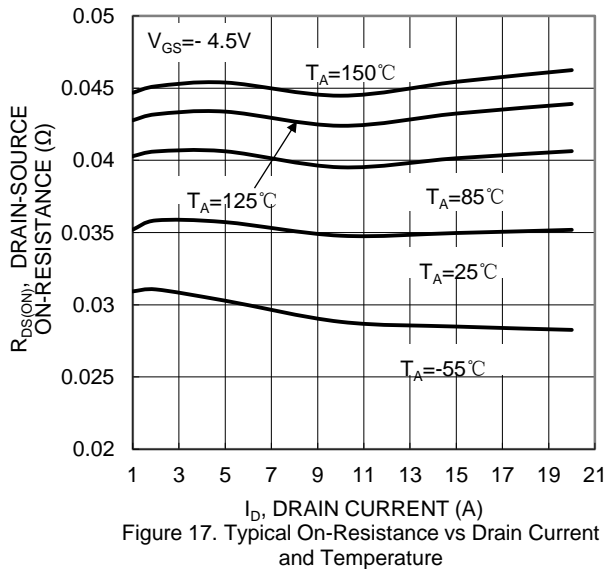
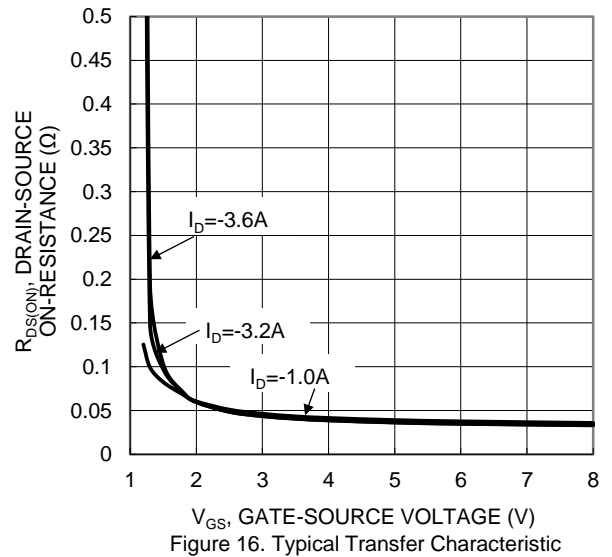
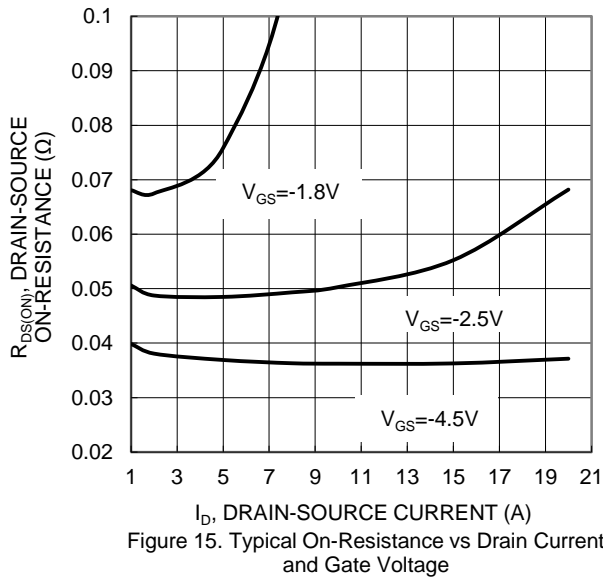
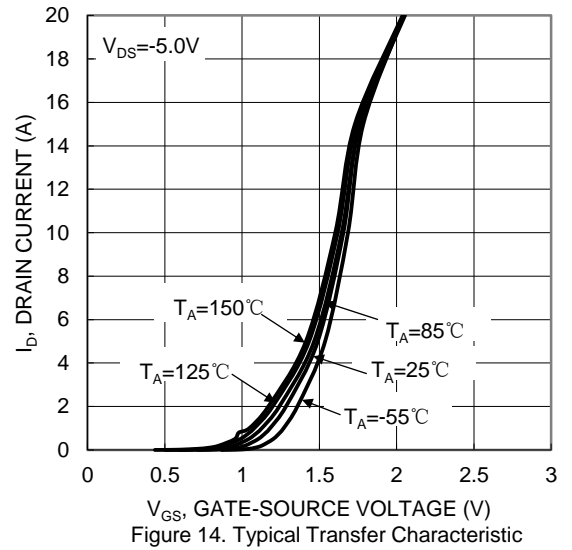
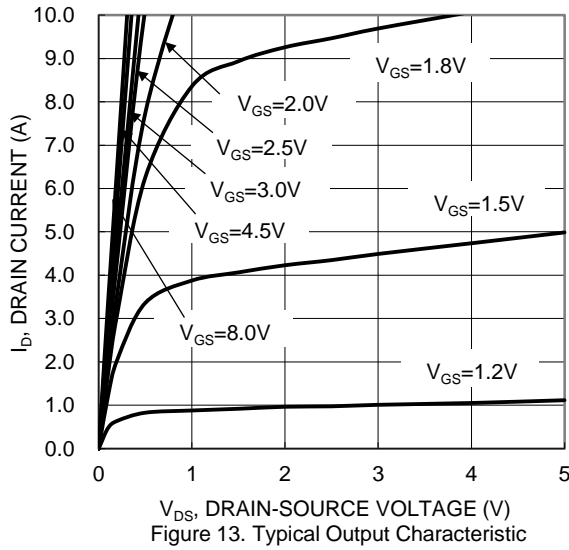
Notes: 6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to product testing.

Typical Characteristics - N-CHANNEL





Typical Characteristics - P-CHANNEL



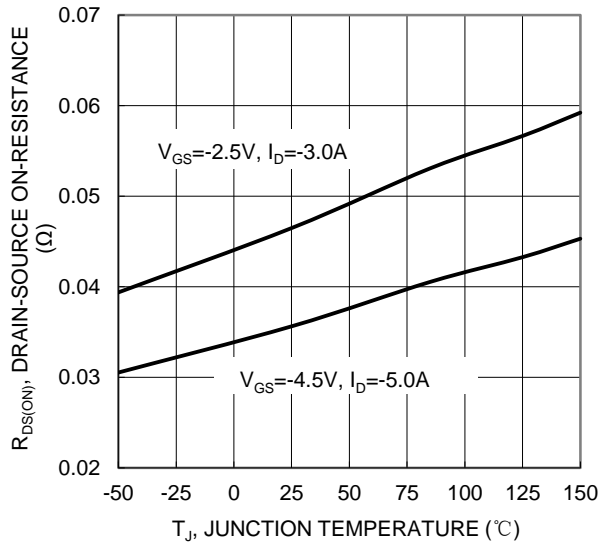


Figure 19. On-Resistance Variation with Temperature

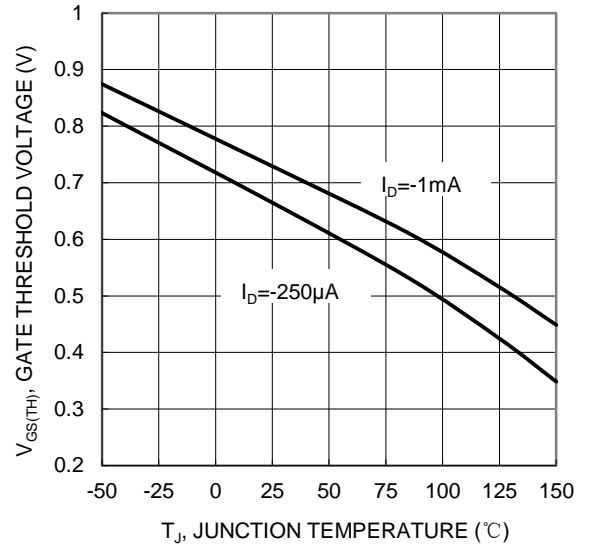


Figure 20. Gate Threshold Variation vs Junction Temperature

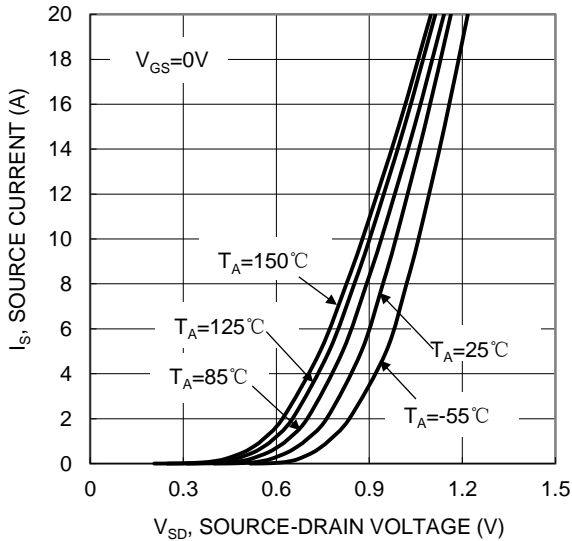


Figure 21. Diode Forward Voltage vs. Current

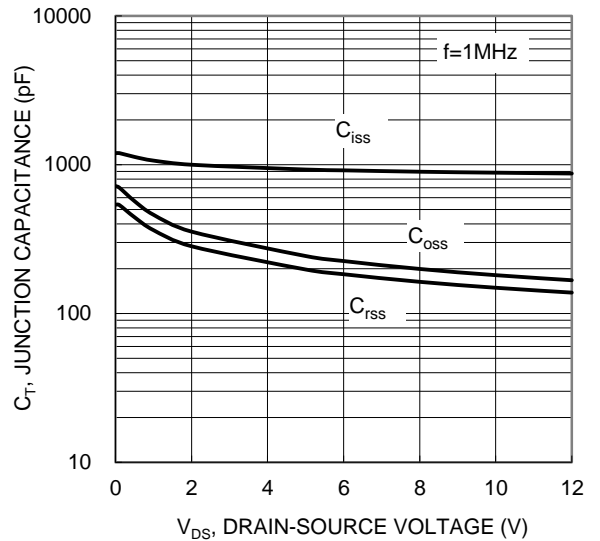


Figure 22. Typical Junction Capacitance

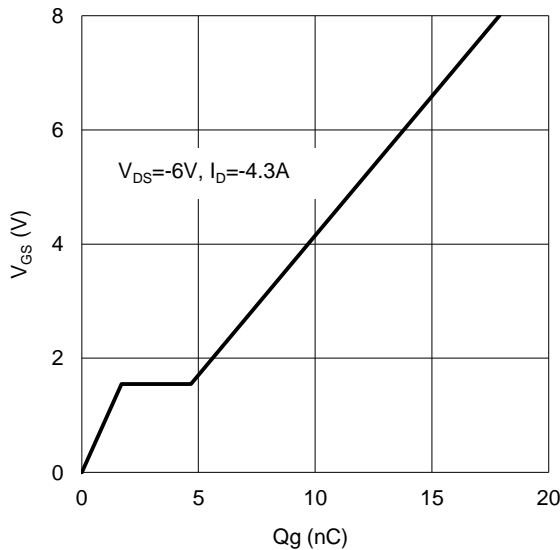


Figure 23. Gate Charge

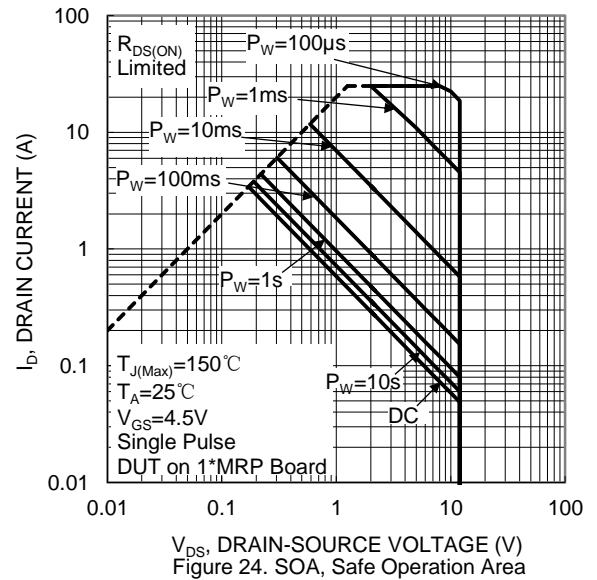
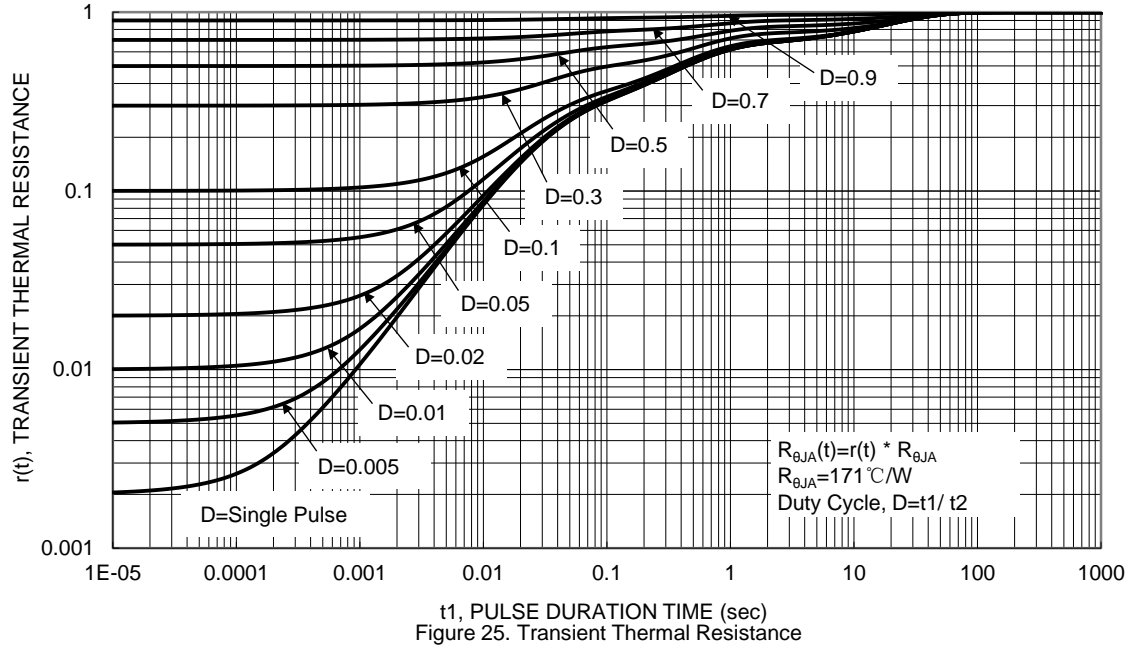
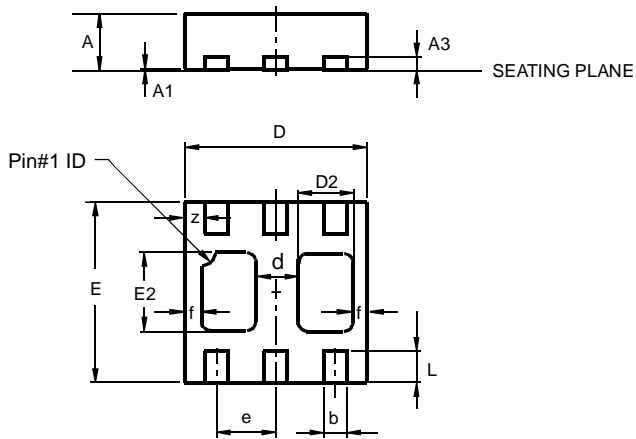


Figure 24. SOA, Safe Operation Area



Package Outline Dimensions

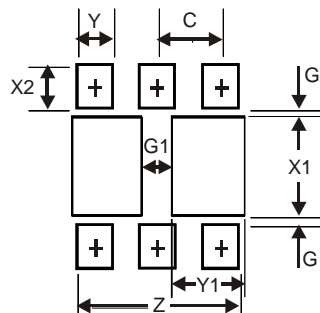
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



U-DFN2020-6 Type B			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0	0.05	0.02
A3	—	—	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
d	—	—	0.45
D2	0.50	0.70	0.60
e	—	—	0.65
E	1.95	2.075	2.00
E2	0.90	1.10	1.00
f	—	—	0.15
L	0.25	0.35	0.30
z	—	—	0.225
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
C	0.65

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